

### NPN SILICON PLANAR EPITAXIAL TRANSISTOR

# BF959

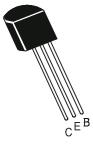
CEB

TO-92 Plastic Package

# BF 959 IS A SILICON NPN TRANSISTOR INTENDED FOR USE AT VERY HIGH FREQUENCIES.

ABSOLUTE MAXIMUM RATINGS (Ta=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	VALUE	UNIT	
Collector Emitter Voltage	V <sub>CEO</sub>	20	V	
Collector Base Voltage	V <sub>CBO</sub>	30	V	
Emitter Base Voltage	$V_{EBO}$	3	V	
Collector Current Continuous	I <sub>C</sub>	100	mA	
Power Dissipation @ Ta=25 <sup>o</sup> C	PD	625	mW	
Derate Above 25°C		5.0	mW/ºC	
Power Dissipation @ Tc=25 <sup>o</sup> C	PD	1.5	W	
Derate Above 25°C		12	mW/ºC	
Operating And Storage Junction	T <sub>j</sub> , T <sub>stg</sub>	-55 to +150	°C	
Temperature Range				
THERMAL RESISTANCE				
Junction to ambient	R <sub>th(j-a)</sub>	200	°C/W	
Junction to case	R <sub>th(j-c)</sub>	83.3	ºC/W	



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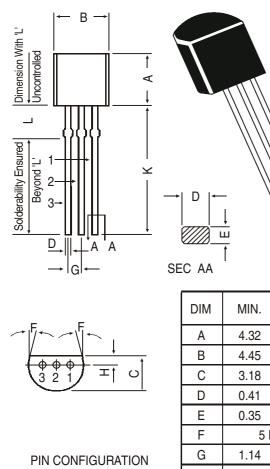
### ELECTRICAL CHARACTERISTICS (Ta=25°C unless specified otherwise)

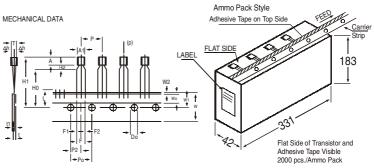
			VALUE				
DESCRIPTION	SYMBOL	_ TEST CONDITION	MIN	TYP	MAX	UNIT	
Collector Emitter Breakdown Voltage	$BV_{CEO}$	I <sub>C</sub> =1mA,I <sub>B</sub> =0	20			V	
Collector Base Breakdown Voltage	$BV_{CBO}$	$I_{C}=10\mu A, I_{E}=0$	30			V	
Emitter Base Breakdown Voltage	$BV_{EBO}$	I <sub>E</sub> =10μΑ, I <sub>C</sub> =0	3			V	
Collector Cut off Current	I <sub>CBO</sub>	$V_{CB}=20V, I_{E}=0$			100	nA	
DC Current Gain	$h_{FE}$	V <sub>CE</sub> =10V,I <sub>C</sub> =5mA	35				
		$V_{CE}$ =10V,I <sub>C</sub> =20mA	40				
Base Emitter Saturation Voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =30mA,I <sub>B</sub> =2mA			1.0	V	
Collector Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =30mA,I <sub>B</sub> =2mA			1.0	V	
DYNAMIC CHARACTERSTICS							
Transition Frequency	f <sub>T</sub>	I <sub>C</sub> =20mA, V <sub>CE</sub> =10V, f=100MHz	700			MHz	
		I <sub>C</sub> =30mA, V <sub>CE</sub> =10V, f=100MHz	600			MHz	
Common Emitter Feedback Capacitance	C <sub>re</sub>	$V_{CB}$ =10V, f=10MHz		0.65		pF	
Noise Figure	NF	I <sub>C</sub> =4mA, V <sub>CE</sub> =10V Rs=50Ω, f=200MHz		3.0		dB	

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### **TO-92 Transistors on Tape and Ammo Pack**

### All dimensions in mm unless specified otherwise

ITEM		SPECIFICATION			N		
TEM	SYMBOL	MIN.	NOM.	MAX.	TOL .	REMARKS	
BODY WIDTH	A1	4.0		4.8			
BODY HEIGHT BODY THICKNESS	A T	4.8 3.9		5.2 4.2			
PITCH OF COMPONENT	P	5.5	12.7	4.2	±1		
FEED HOLE PITCH	Po		12.7		±0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH	
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		±0.4	TO BE MEASURED AT BOTTOM OF CLINCH	
DISTANCE BETWEEN OUTER LEADS COMPONENT ALIGNMENT	F ∆h		5.08 0	1	+0.6 -0.2	AT TOP OF BODY	
TAPE WIDTH HOLD-DOWN TAPE WIDTH HOLE POSITION	W Wo W1		18 6 9		±0.5 ±0.2 +0.7 -0.5		
HOLD-DOWN TAPE POSITION LEAD WIRE CLINCH HEIGHT COMPONENT HEIGHT	Ho H1		0.5 16	23.25	±0.2 ±0.5		
LENGTH OF SNIPPED LEADS FEED HOLE DIAMETER TOTAL TAPE THICKNESS	L Do t		4	11.0 1.2	±0.2	t1 0.3 - 0.6	
LEAD - TO - LEAD DISTANCEF1,	F2		2.54		+0.4		
CLINCH HEIGHT PULL - OUT FORCE	H2 (P)	6N		3	0.1		

1. BASE

- EMITTER 2.
- 3. COLLECTOR

DIM	MIN.	MAX.			
А	4.32	5.33			
В	4.45	5.20			
С	3.18	4.19			
D	0.41	0.55			
Е	0.35	0.50			
F	5 DEG				
G	1.14	1.40			
Н	1.14	1.53			
K	12.70				
L	1.982	2.082			

All diminsions in mm.

NOTES

MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.
MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20

PITCHES. 3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO

EXPOSURE OF ADHESIVE. 4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED. 5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT. 6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.

# **Packing Detail**

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

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